

10-19-05

Docket No. JCLA17344

Form 1595  
1-31-92

10-28-2005

IEET

U.S. Department of Commerce  
Patent and Trademark Office



112975 U.S. PTO  
11/255710



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To the Honorable Assistant Commissioner for Patents: Please record the attached  
original documents or copy thereof.

|   |  |   |  |
|---|--|---|--|
| 1. Name of conveying party(ies):<br><br>Geng-Shin Shen  |  | 2. Name/address of receiving Party(ies):<br><br>ChipMOS TECHNOLOGIES INC.<br>No. 1, R&D 1st Rd., Science-Based<br>Industrial Park Hsinchu, Taiwan, R.O.C.<br><br>ChipMOS Technologies (Bermuda) LTD.<br>Canon's Court , 22 Victoria Street ,<br>Hamilton HM12 , Bermuda |  |
| 3. Nature of conveyance: <input checked="" type="checkbox"/> Assignment<br><input type="checkbox"/> Merger <input type="checkbox"/> Security Agreement <input type="checkbox"/> Other<br><input type="checkbox"/> Change of Name <input type="checkbox"/> Reassignment                                      |  | Add'l names of receiving parties<br>Attached? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No   |  |
| 4. Date(s) of execution: <u>September 26, 2005.</u>   |  |   |  |
| 5. Application number(s) or patent number(s):<br><b>If this documents is being filed together with a new application, the execution date of the application is <u>September 26, 2005.</u></b>   |  |   |  |
| A. Patent Application No. (s)<br><br>Additional numbers attached ? <input type="checkbox"/> Yes <input checked="" type="checkbox"/> No  |  | B. Patent No. ( s)  |  |
| 6. Name and address of party to whom Correspondence concerning document should be mailed:<br><br>J.C. Patents, Inc.<br>4 Venture, Suite 250<br>Irvine, CA 92618<br>(949) 660-0761   |  | 7. Total No. of applications and patents involved:<br>ONE(1)  |  |
|   |  | 8. Total fee (37 CFR §3.41): <u>\$40.00</u><br><input checked="" type="checkbox"/> Enclosed<br><input type="checkbox"/> Charge to Acct. No. _____   |  |
|   |  | 9. Total number of pages, including Cover sheet, attachments and document <u>3</u> .  |  |
| DO NOT USE THIS SPACE   |  |   |  |
| 10. Statement and Signature:<br><br>To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.<br><br><u>Jiawei Huang</u> <u>[Signature]</u> <u>10/19/2005</u><br>Name of Person Signing      Signature      Date |  |   |  |

Registration No. 43,330

10/27/2005 ECOOPER 00000085 11255710

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PATENT  
REEL: 017126 FRAME: 0573

## ASSIGNMENT

WHEREAS,

1. Geng-Shin Shen

hereinafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: **STACKED-TYPE CHIP PACKAGE STRUCTURE**

☐ Filed: Serial No.

☒ Executed concurrently with the execution of this instrument

WHEREAS, ChipMOS TECHNOLOGIES INC.  
of No. 1, R&D 1st Rd., Science-Based Industrial Park Hsinchu, Taiwan, R.O.C.

ChipMOS Technologies (Bermuda) LTD.  
of Canon's Court , 22 Victoria Street , Hamilton HM12 , Bermuda

hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same:

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee Lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

## ASSIGNMENT CONTINUED

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

Signature: Geng-Shin Shen Date: 8/26/05

Sole or First Joint Inventor: Geng-Shin Shen